



ATLAS Pixel and Strip Radiation Damage Studies

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31st RD50 Workshop

20/11/17

Overview

Motivation

Detector layout IBL Pixel SCT

Radiation Types

NIEL fluence Total Ionising Dose

Measurements

Leakage currents; IBL, Pixel and SCT Readout chip current consumption; IBL Depletion voltages; IBL, Pixel and SCT Lorentz Angle; IBL and Pixel Charge collection efficiency; IBL and pixel

Summary

Motivation

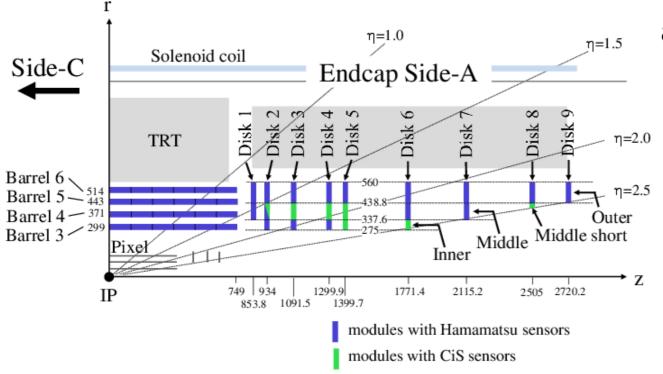
Radiation damage is a key parameter affecting the performance of the silicon modules used in ATLAS

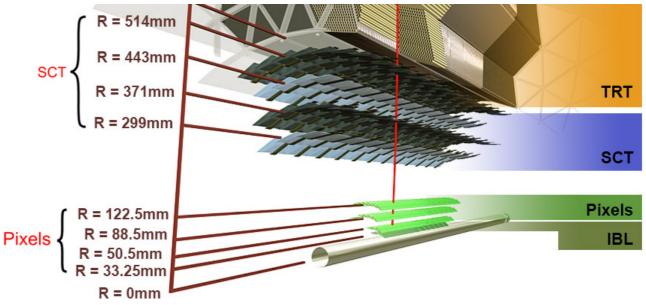
ATLAS have simulations which predict the radiation levels in the ATLAS detector; we can

use these simulations to predict future performance of detector

Imperative we check the accuracy of these

simulations and predictions of other sensor parameters, affected by radiation damage





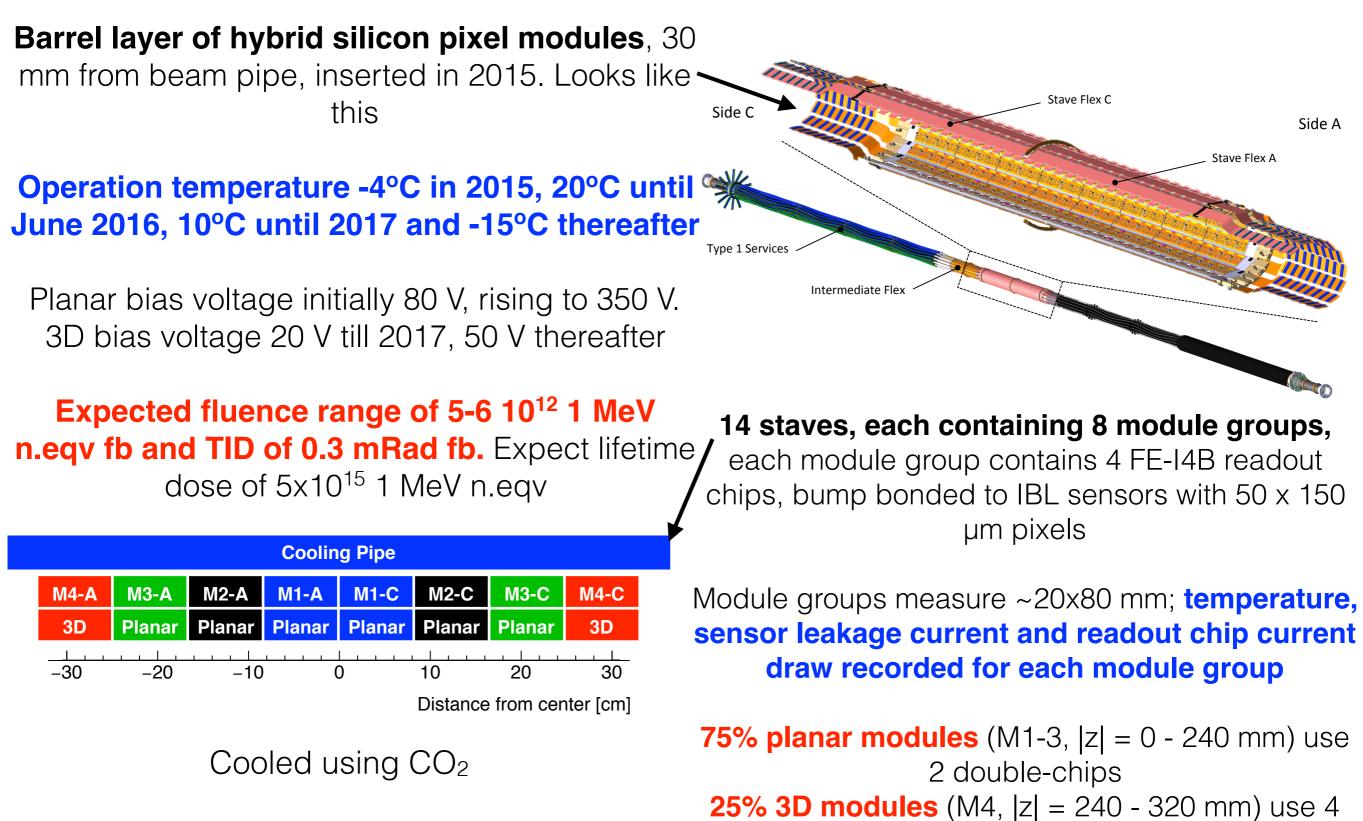
Results of these **measurements are fed back to ATLAS Radiation Simulation group**, can also be used to optimise operation conditions, and future detector designs

We also **use radiation damage measurements as inputs for simulations** of detector performance; see Ben Nachman's talk!

We have studies from IBL, Pixel and SCT

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Detector layout: IBL



single chips

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Detector layout: Pixel

3 barrel layers of hybrid silicon pixel modules,

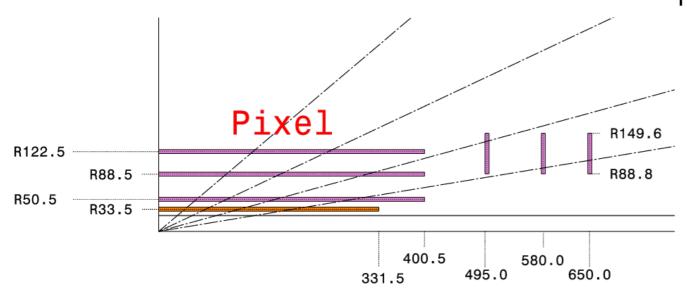
50, 88 and 122 mm from beam, called B-layer, layer 1 and layer 2, with **3 disk layers** at end. Looks like this _____

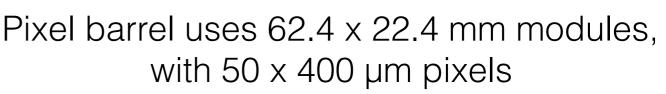
Operation temperature -13°C in Run 1, -10°C in ^{430mm} Run 2

Bias voltage initially 150 V, currently 350 V

Expected fluence range of 0.8-2.9 10¹² 1 MeV n.eqv fb and TID of 0.16 mRad fb. (~ 50% IBL)

Expect lifetime dose of 2x10¹⁵ 1 MeV n.eqv





End-cap disk layers

Barrel Layer 0 (b-layer)

Sensors read-out using FE-13 chips, bump-bonded to sensors

Cooled using C₃F₈ evaporative cooling system

1442mm

Barrel Layer 2

Barrel Layer 1

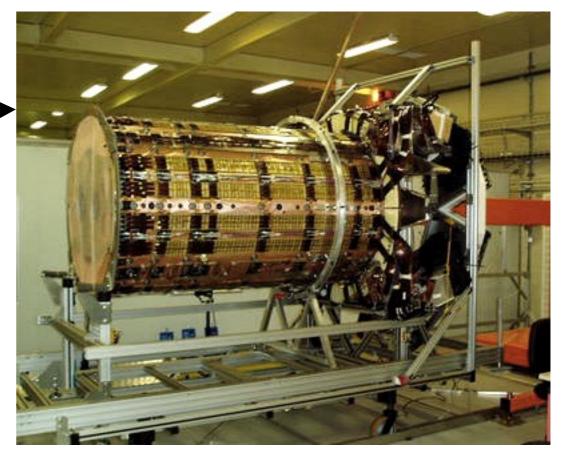
Detector layout: SCT

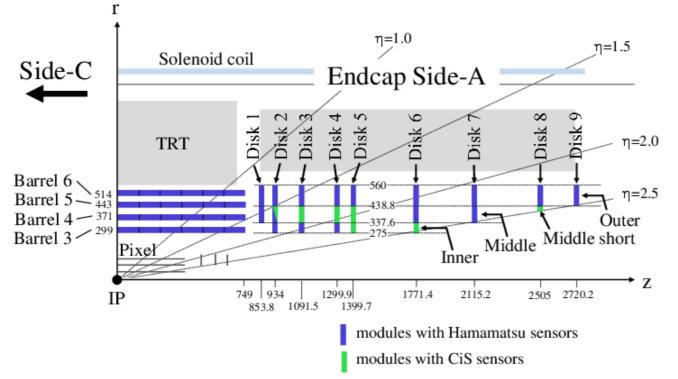
4 barrel layers of silicon strips, 300-514 mm
 from beam, labelled Barrel 3-6 respectively. 9
 disk layers at end. Looks like this!

Operation temperature ~-2°C for layers B3-5, ~8°C for layer B6 and disks

Initial bias at 150 V, rising to 450 V over lifetime

Expected fluence range of 0.2-0.3 10¹² 1 MeV n.eqv fb and TID of 0.02 mRad fb (~5% of IBL)





SCT uses ~60 x 60 mm sensors, with ~80 μm strip pitch

Sensors read-out using custom ABCD3TA ASIC

Cooled using C₃F₈ evaporative cooling system

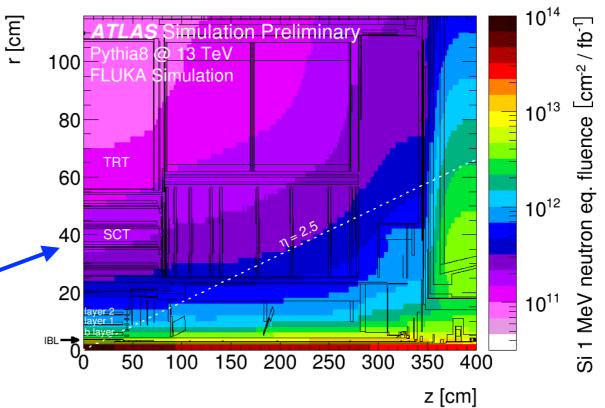
Radiation Types: NIEL fluence

Main radiation damage mechanism for sensors is from Non Ionising Energy Losses (NIEL)

Fluence is proportional to integrated luminosity, the ATLAS Radiation Simulation group calculates fluence rate for all areas of the ATLAS detector, using Pythia and FLUKA

We convert integrated luminosity to fluence, using the fluence rate [10¹⁴ 1 MeV n.eqv cm⁻² per fb⁻¹]

> Fluence also affects depletion voltage of sensors; predicted by Hamburg model



Hamburg/Sheffield-Harper models can accurately predict sensor leakage current as a

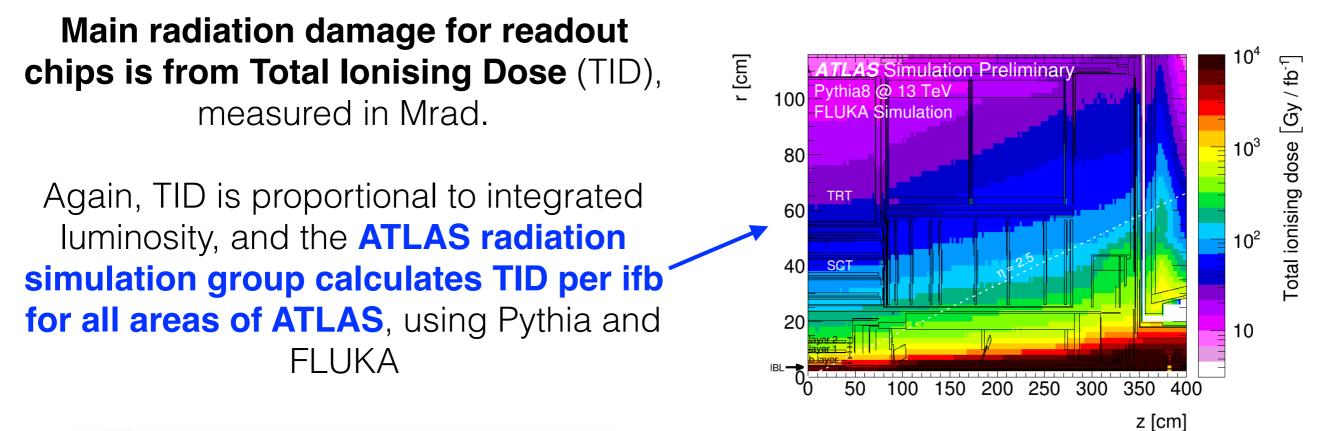
function of fluence, temperature and time. Hamburg model was validated at 20-80°C.

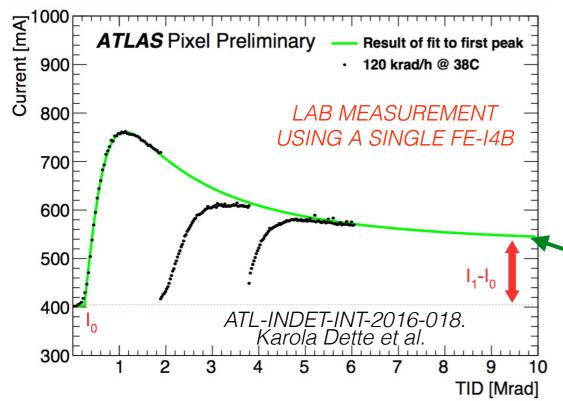
Can measure the fluence rate for a sensor by plotting leakage current against integrated luminosity, and fitting the Hamburg model to measurements

More information on simulations in Paul Miyagawa's talk

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Radiation Types: TID





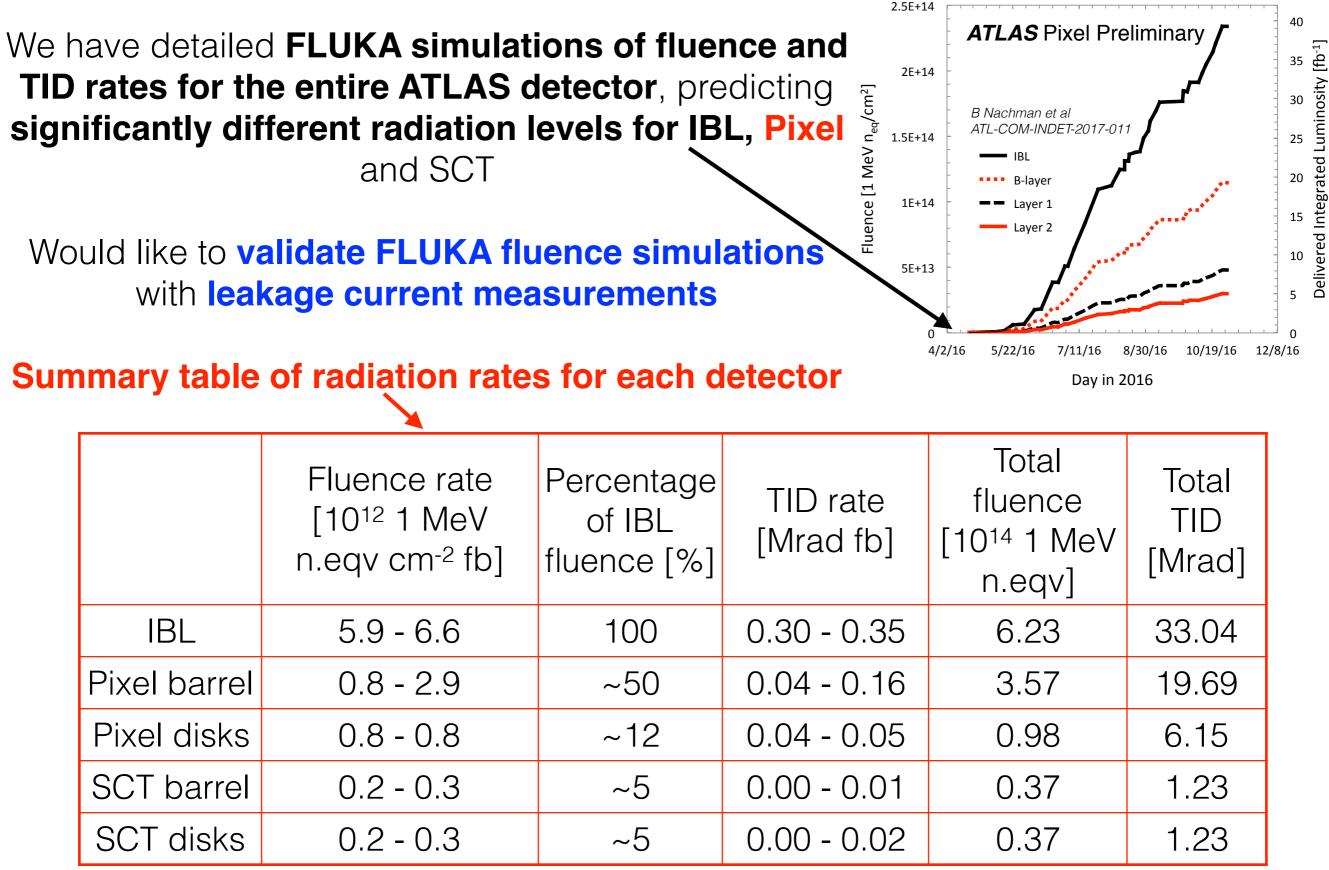
TID affects readout chip current consumption; there is not yet a model which accurately predicts this; <u>see</u>

Backhaus paper

At best, can state the maximum expected Current consumption at a given TID

We expect peak IBL current consumption at ~1 Mrad

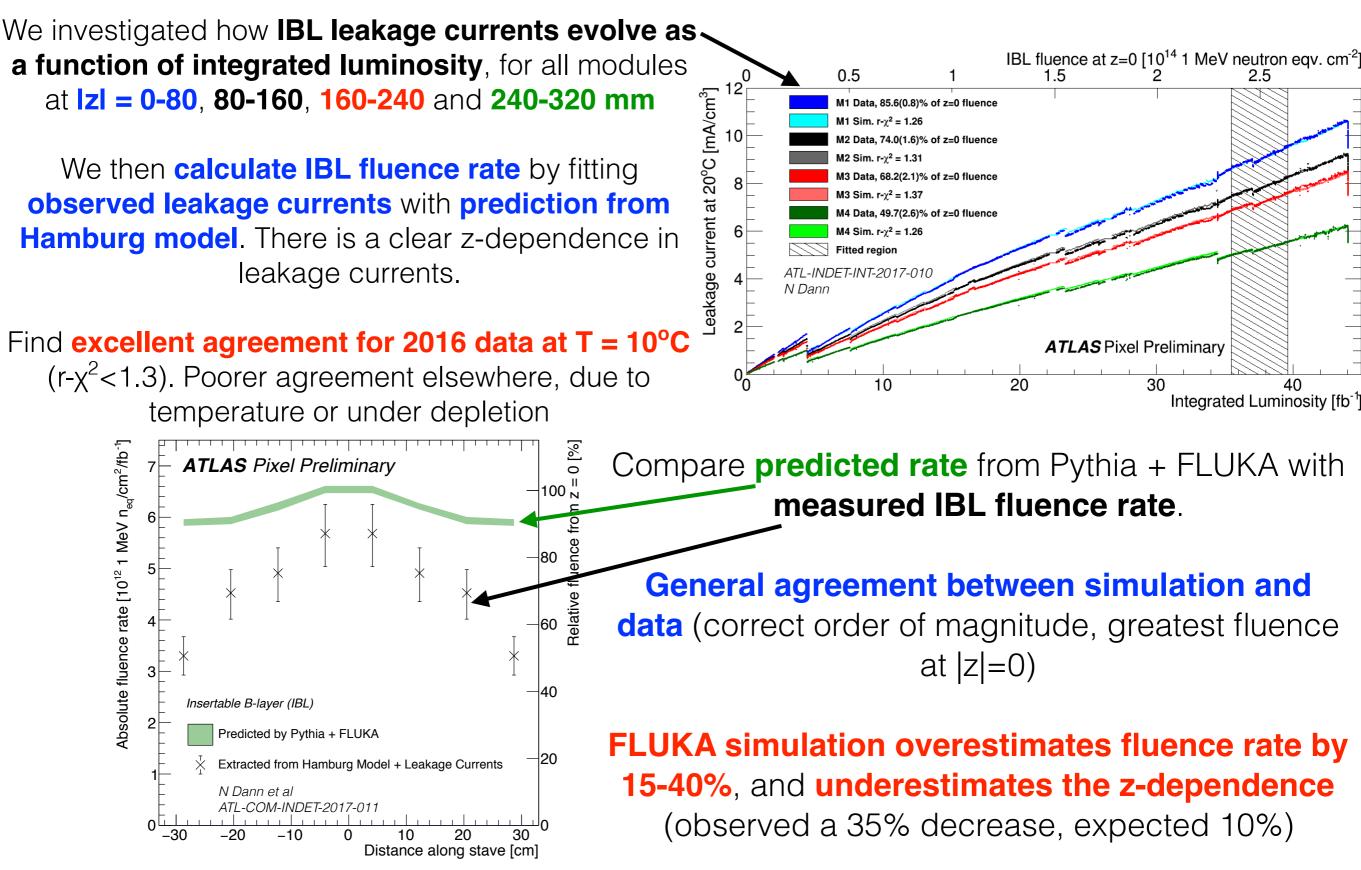
Radiation Types: Summary



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Measurements: IBL leakage currents



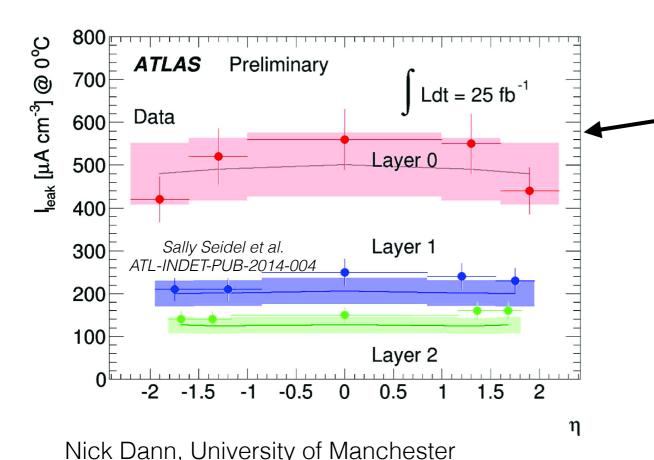
Measurements: Pixel Leakage Currents

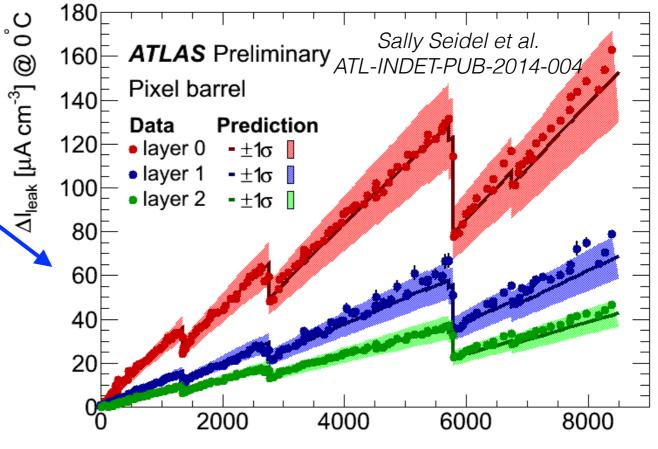
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ATLAS has also **investigated how B-layer leakage currents evolve** as a function of integrated luminosity in Run 1.

Compare observed leakage current with modelled leakage current, using simulated fluence rate values, for **B-layer**, **layer 1 and 2**

General agreement for all layers in Run 1, limited by large uncertainties on fluence-rate simulations



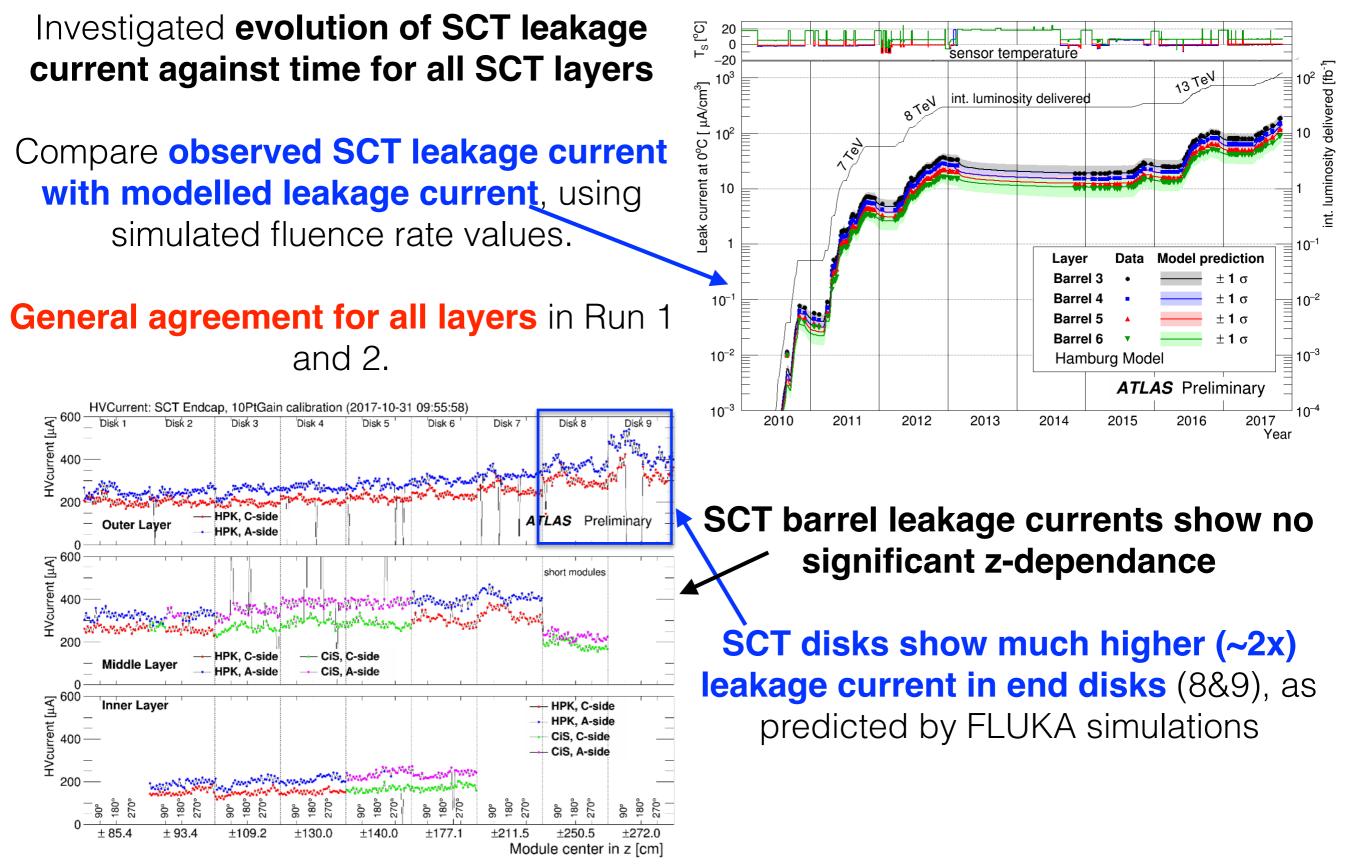


Integrated Luminosity [pb⁻¹]

Also investigated z-dependence of Pixel — leakage current in Run 1 for B-layer, layer 1 and 2

We can clearly **see a similar structure to the IBL**, with higher values in the central regions. **Structure is largest in the B layer, smallest in Layer 2**.

Measurements: SCT leakage currents

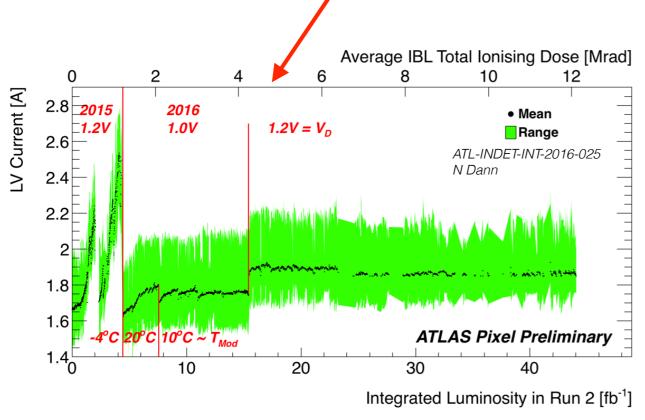


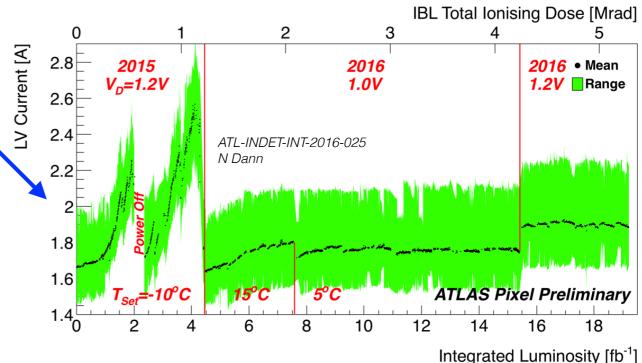
Measurements: IBL Readout Chips

Investigated how IBL readout chip current consumptions evolved

Clearly see **IBL readout chip currents** increased dangerously in 2015. Currents stable in 2016 after increasing operating temperature

Currents have remained stable since





There is not yet a good predictive model for readout chip currents as a function of TID

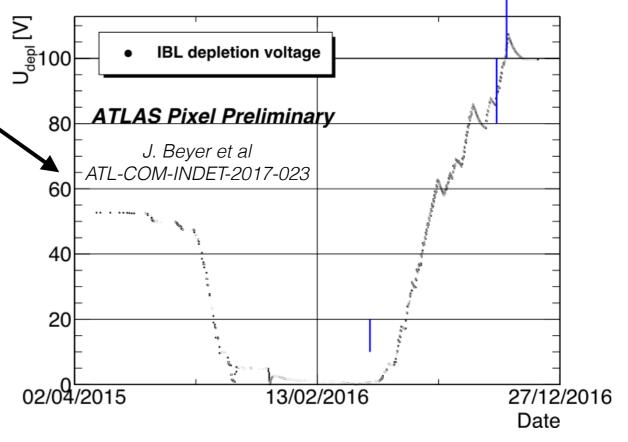
At best, we expected to see a peak in chip current consumption at ~1 Mrad; results are consistent with this

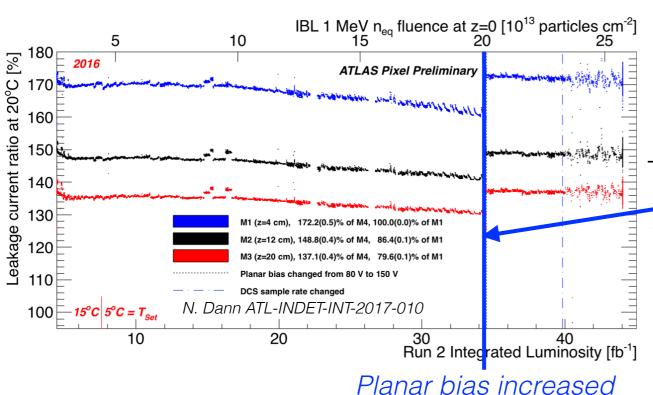
Changes in temperature/operating voltage may have hidden a later peak.

Measurements: IBL Depletion Voltage

Also investigated how **IBL depletion voltages evolve** in IBL planar sensors, comparing **predicted values** from the Hamburg model, against **measured data**

Hamburg model does not account for the first depletion voltage measurement, does accurately predict the rest





The IBL sensors receive different fluence rates, and thus have different leakage currents. The Hamburg model predicts the ratio of leakage currents should be constant for all groups

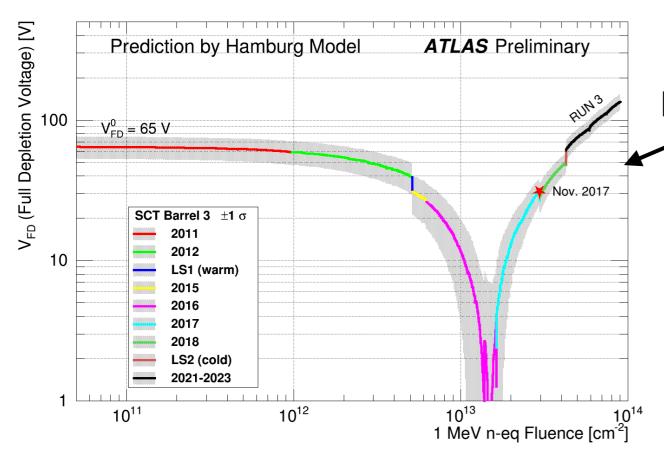
The IBL leakage current ratios are clearly stable after -the increase in planar IBL bias in 2016, as predicted. We compare 3D modules at Izl = 240-320 with planar modules at Izl = 0-80, 80-160, 160-240 mm

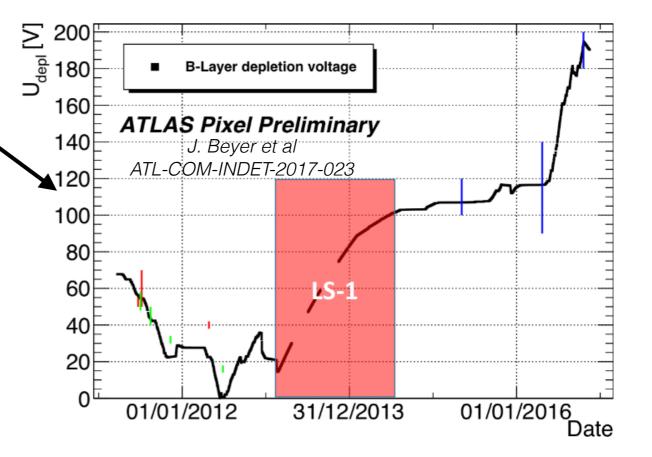
The decrease in leakage current ratios before this is evidence that the modules were under depleted

Measurements: Pixel/SCT Depletion Voltage

Depletion voltages have also been simulated and measured in the B-layer comparing predicted values from the Hamburg model, against measured data in Run 1 and 2

The Hamburg model accurately predicts the measured depletion voltage values





Depletion voltage simulations have also been done for SCT Barrel 3, but no measurements have been made yet

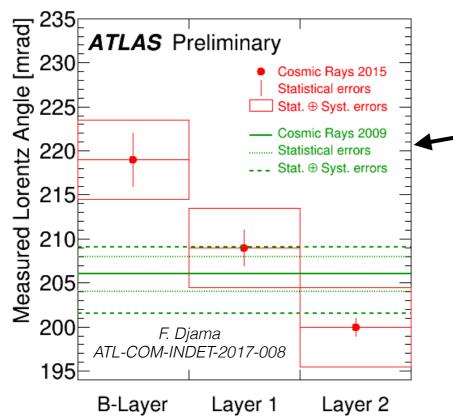
Hamburg model predicts Barrel 3 should have passed the type-inversion point, and that the depletion voltage will approach 200 V by 2023

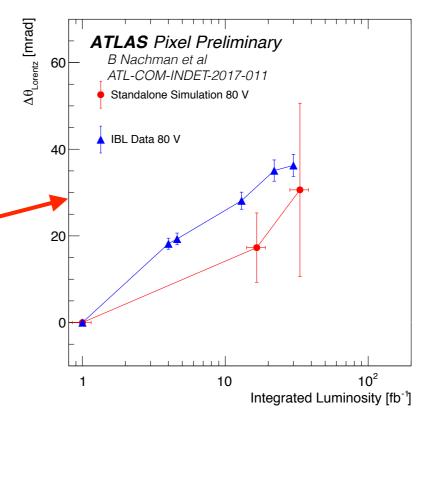
Measurements: Lorentz Angles

Charge carriers in ATLAS's silicon sensors are deflected by a magnetic field, the angle of this deflection is called the Lorentz angle

The Lorentz angle can be measured, and varies as a function of radiation damage. We observethe expected increase of angle with integrated luminosity

See Ben Nachman's talk for details on the simulation





Also found Lorentz angle for Pixel before Run 1 and Run 2

Can clearly see there was **no difference in** Lorentz angle between layers, before Run 1

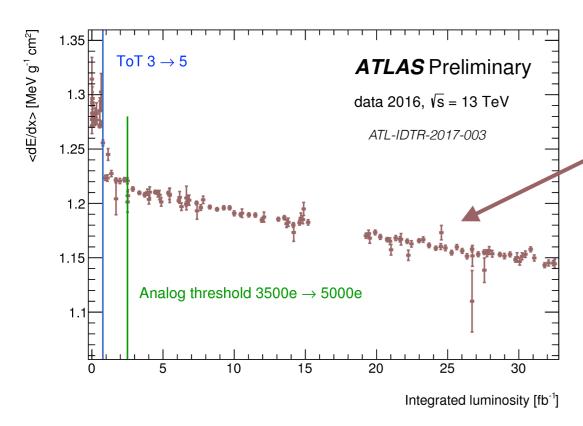
Can clearly see **B-layer has highest Lorentz** angle, Layer-2 has lowest, before Run 2

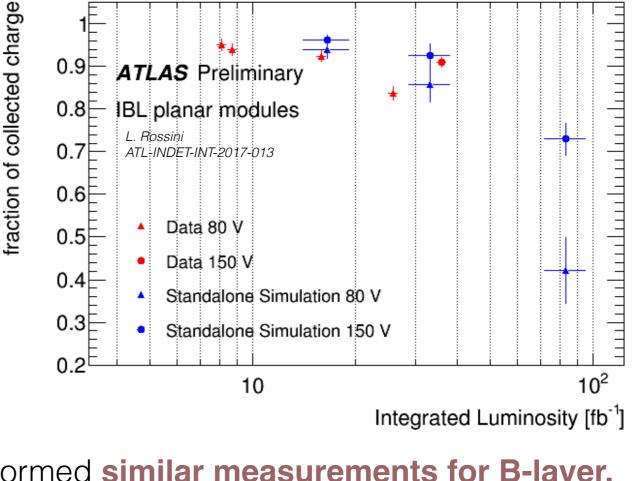
Measurements: IBL and Pixel Charge Collection

Measured how IBL charge collection ---efficiency varied as integrated luminosity increased; expect the efficiency to decrease due to radiation damage

Observe the expected decrease in charge collection efficiency

See Ben Nachman's talk for details on the simulation





Performed similar measurements for B-layer, using dE/dx instead

dE/dx value is related to the charge collection efficiency, and will decrease as radiation damage increases

Can clearly see the **gradual decrease in dE/dx due to radiation damage**, and the step changes, due to changing tuning thresholds in the readout chips

Summary

We have very detailed models of fluence and TID per ifb for the entire ATLAS detector

General agreement between FLUKA simulations and leakage current observations in IBL, B-layer, layer 1 and 2 and SCT

Significant difference in z-dependance of fluence for IBL. Smaller effect seen in Pixel. No z-dependence found for SCT Barrel

IBL readout chips affected by TID, observations consistent with FLUKA TID simulations

Hamburg model predicts depletion voltage evolutions; these generally match measurements in the IBL and B-layer

Lorentz angles have been measured for IBL; values increasing as expected, but observe lower angles than predicted. From pixel measurements, we clearly see highest Lorentz angles in B-layer and lowest in Layer-2

Charge collection efficiency is decreasing in IBL, in line with simulations

Back up

Temperature normalisation

(eq. 1)
$$\frac{\Delta I}{V}(\Phi,T,t) = \alpha(T,t) \cdot \Phi = R(T) \cdot \alpha(T_R,t) \cdot \Phi$$

where R(T) is the ratio between the leakage current measured at temperature T and a certain reference temperature T_R . R(T) is given by [6] as:

(eq. 2)
$$R(T) = \frac{I(T_R)}{I(T)} = \left(\frac{T_R}{T}\right)^2 \exp\left(-\frac{E_g}{2k_B}\left[\frac{1}{T_R} - \frac{1}{T}\right]\right).$$

In this work all presented data have been normalized to $T_R = 20^{\circ}$ C using an effective energy gap of $E_g = 1.12$ eV. Most previously reported data on the annealing of the leakage current have been parameterized with a normalized annealing function g(t) consisting of a sum of exponentials [7,8]

http://citeseerx.ist.psu.edu/viewdoc/download?doi=10.1.1.55.2759&rep=rep1&type=pdf

[6] : S.M. Sze, Physics of Semiconductor Devices, 2nd ed. (Wiley, 1984)

Leakage current dependence on fluence

Change in leakage current (Δ I) in silicon sensors **mostly due to** electron-hole pair generation at radiation-induced **defects in sensor bulk**

Bulk defects mainly created by NIEL, number of defects increases ~linearly with fluence (Φ_{eq}) , and leakage current should be ~proportional to fluence, mathematically where \mathscr{V} is the

sensor volume and α is the damage function

 $\Delta I = \alpha \ \Phi_{eq} \mathcal{V}$

Complication; defects can anneal over time, with greater annealing at higher temperature => expect leakage current to decrease over time, => add time (\underline{t}) and temperature (T_k) dependence to damage function α . Also add empirical ln term to account for long-term effects

$$\alpha(t, T_k) = \alpha_1 \exp(-t/\tau_1) + \alpha_0 - \beta \ln(t/t_0)$$

Final complication; $\alpha(t, T_k)$ is only valid for a single irradiation. IBL is irradiated multiple times => instead find and update $\alpha(t, T_k)$ and ϕ for each luminosity block, then sum them together to find total ΔI , i.e.

$$\Delta I = \sum \alpha_i \, \Phi_i \, \mathcal{V}$$

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 $\Delta I = \sum \alpha_i \, \Phi_i \, \mathcal{V}$

(current = sum of all alpha parameters * fluence * volume)

Finally, substitute fluence = constant conversion factor * integrated luminosity ($\Phi_i = F * L_i$) can see that $\Delta I = F * \sum \alpha_i * L_i$

For IBL, all modules should have same alphas, any differences in fluence should result in proportional differences in leakage current; i.e.

 $\Delta I_1 / \Delta I_2 = F_1 / F_2$ (current 1 / current 2 = conversion factor 1 / conversion factor 2)

Test this on next slide by plotting relative leakage currents in each module group (i.e. plot I_{module group 1} / I_{module group 4})

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Can we predict leakage currents?

Record time (t), mean temperature (T_k) and use these to find the damage function α^i for every lumi block, and the evolution of all previous α^i s

Find lumi delivered in every lumi block, convert to fluence (Φ^{i}_{eq})

Multiply all α^{i} s by relevant Φ^{i}_{eq} , sum results to find total α

Temperature dependence studied in range 20 - 100 C, we're at ~10C. Recent studies find greater than expected annealing at room temperature => **model will** likely underestimate annealing and **overestimate leakage current**

Hamburg model parameterisation values

Change in leakage current (ΔI) with fluence (Φ_{eq}), where V is the sensor volume and α is the damage function

 $\Delta I = \alpha \ \Phi_{eq} \ V$

Time (t) and temperature (T_k) dependence of damage function α $\alpha(t, T_R) = \alpha_1 \exp(-t/\tau_l) + \alpha_0 - \beta \ln(t/t_0)$

$$\alpha_{1} = 1.23 \times 10^{-17} \text{ A/cm}$$

$$1/\tau_{I} = k_{0I} \exp(\text{ E}_{I}/(k_{B} * T_{k}))$$

$$k_{0I} = 1.2 \times 10^{13} \text{ s}^{-1}$$

$$\text{E}_{I} = 1.11 \text{ eV}$$

$$k_{B} = 8.62 \times 10^{-5} \text{ eV/K}.$$

$$\alpha_{0} = -8.9 \times 10^{-17} \text{ A/cm} + (4.6 \times 10^{-14} / T_{k}) \text{ A K/cm}$$

$$\beta = 2.9 \times 10^{-18} \text{ A/cm}$$